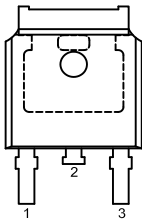


Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I _{GT}	gate trigger current	V _D = 12 V; I _T = 0.1 A; T _j = 25 °C; Fig. 8		20	50	200	µA
Dynamic characteristics							
dV _D /dt	rate of rise of off-state voltage	V _{DM} = 436 V; T _j = 125 °C; R _{GK} = 100 Ω; (V _{DM} = 67% of V _{DRM}); exponential waveform; Fig. 13		50	100	-	V/µs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 DPAK (SOT428)	
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BT151S-650S	DPAK	plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)	SOT428

7. Marking

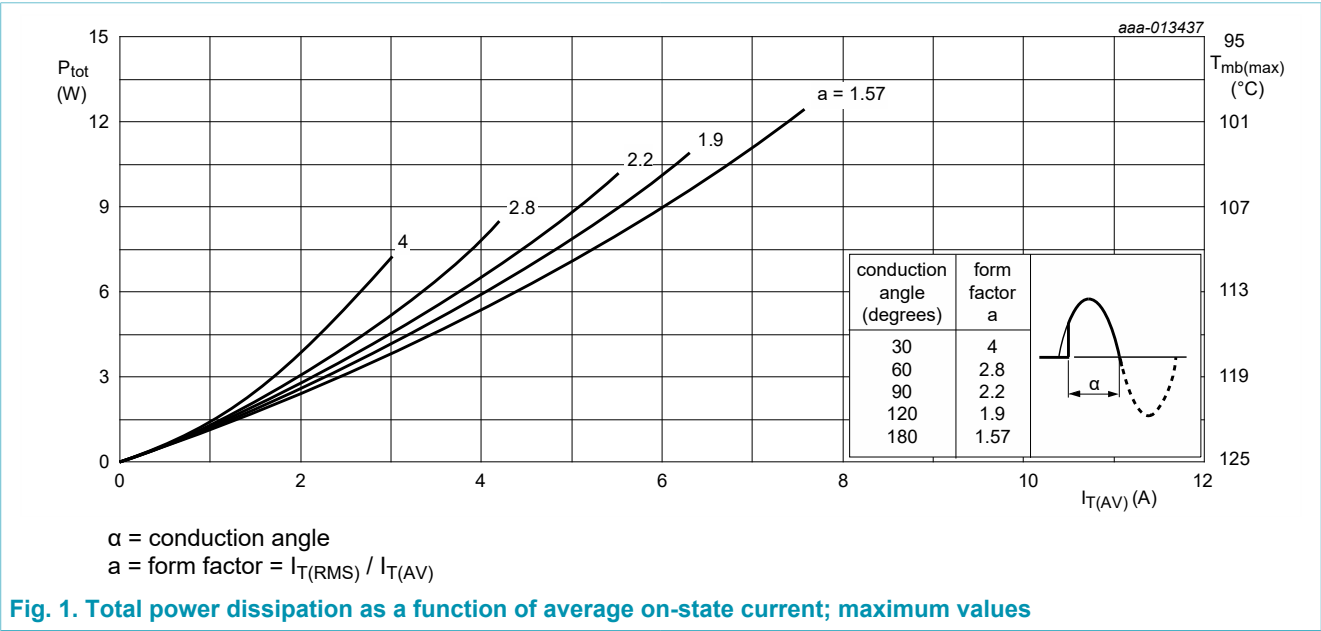
Table 4. Marking codes

Type number	Marking code
BT151S-650S	BT151S-650S

8. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	650	V
V_{RRM}	repetitive peak reverse voltage		-	650	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 100\text{ }^{\circ}\text{C}$; Fig. 1	-	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 100\text{ }^{\circ}\text{C}$; Fig. 2; Fig. 3	-	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 10\text{ ms}$; Fig. 4; Fig. 5	-	90	A
		half sine wave; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; $t_p = 8.3\text{ ms}$	-	100	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; SIN	-	41	A^2s
di_T/dt	rate of rise of on-state current	$I_G = 50\text{ mA}$	-	50	$\text{A}/\mu\text{s}$
I_{GM}	peak gate current		-	2	A
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T_{stg}	storage temperature		-40	150	$^{\circ}\text{C}$
T_j	junction temperature		-	125	$^{\circ}\text{C}$



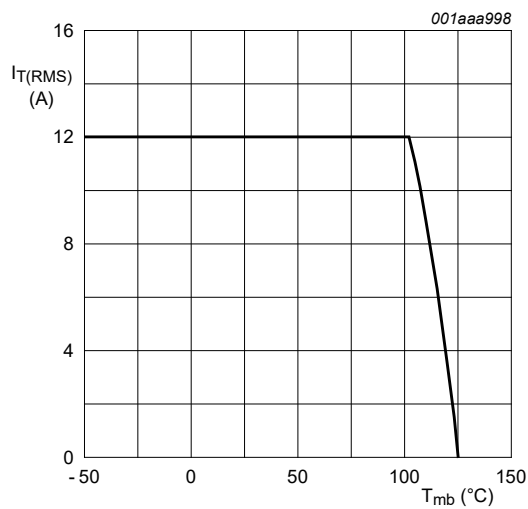
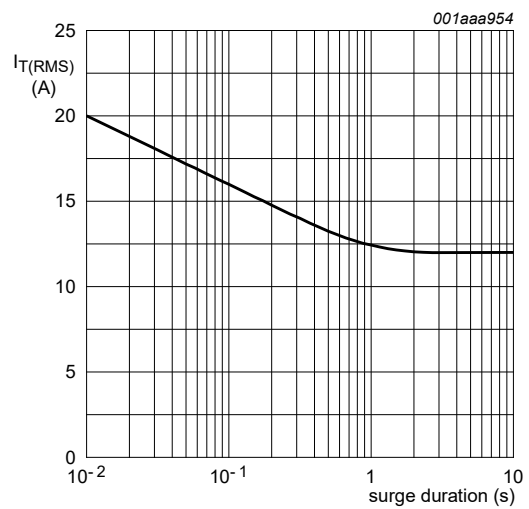
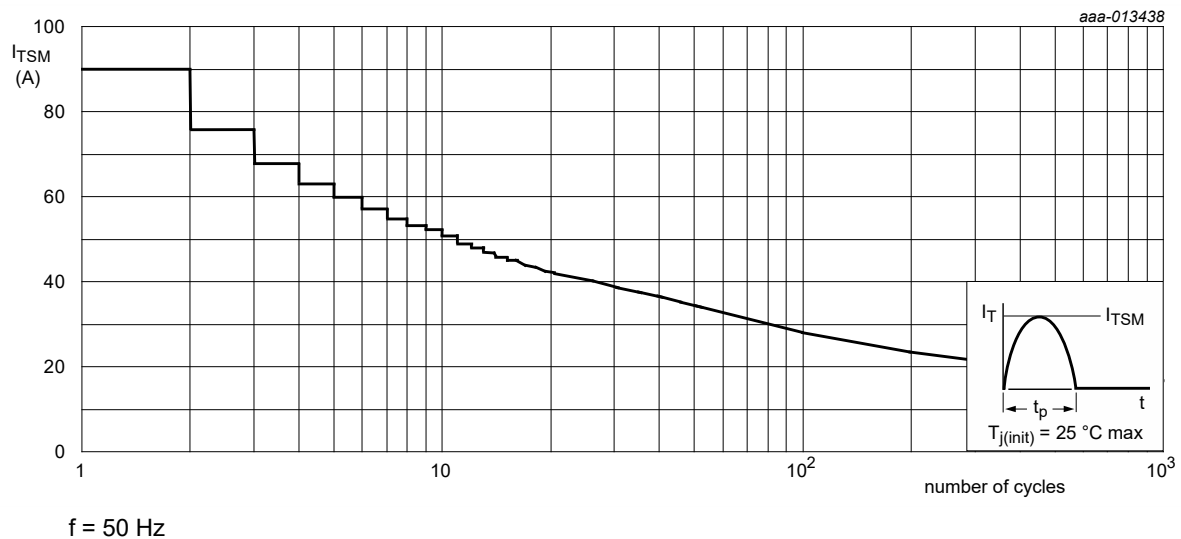


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



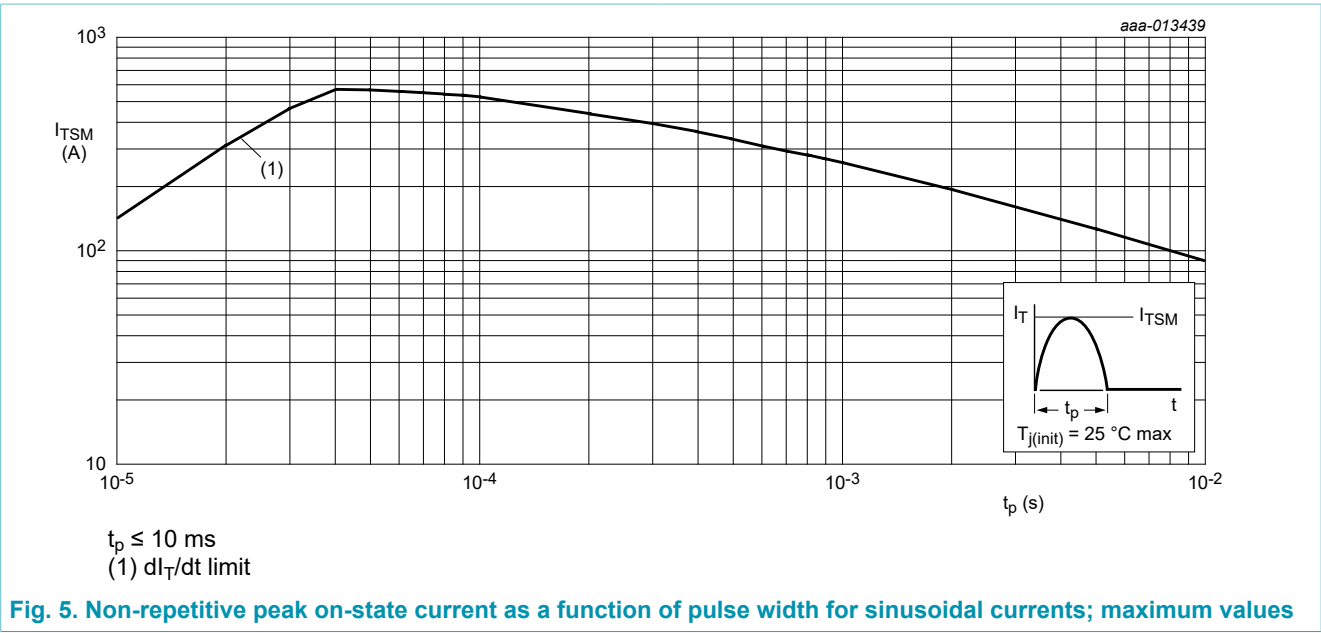
$f = 50 \text{ Hz}$; $T_{mb} = 103 \text{ °C}$

Fig. 3. RMS on-state current as a function of surge duration; maximum values



$f = 50 \text{ Hz}$

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	mounted on an FR4 printed-circuit board; Fig. 7		-	7	-	K/W

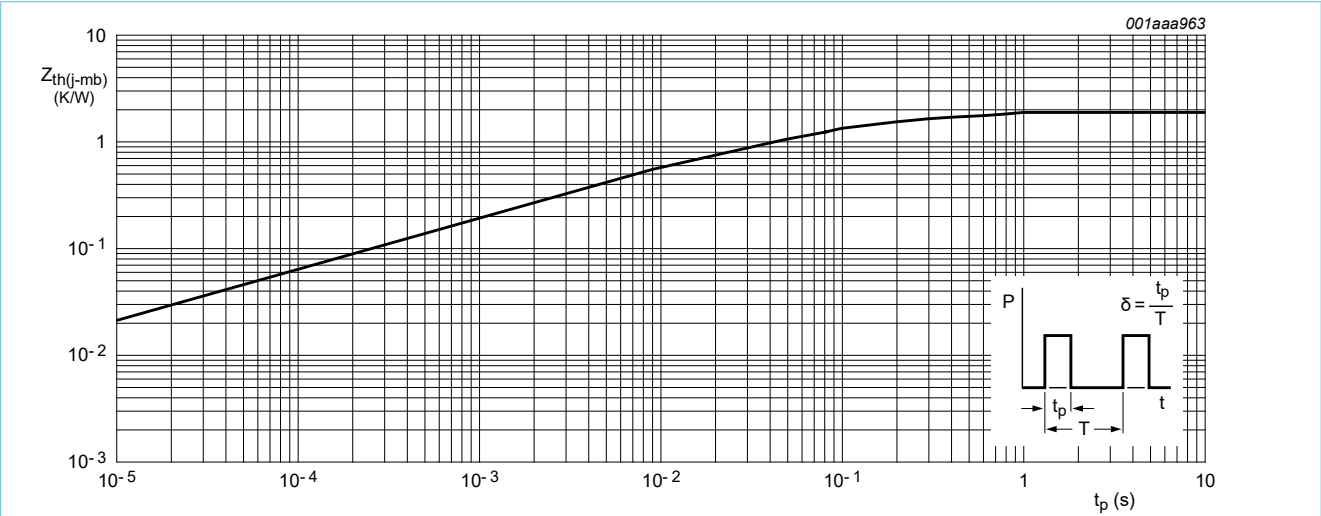


Fig. 6. Transient thermal impedance from junction to mounting base as as function of pulse width

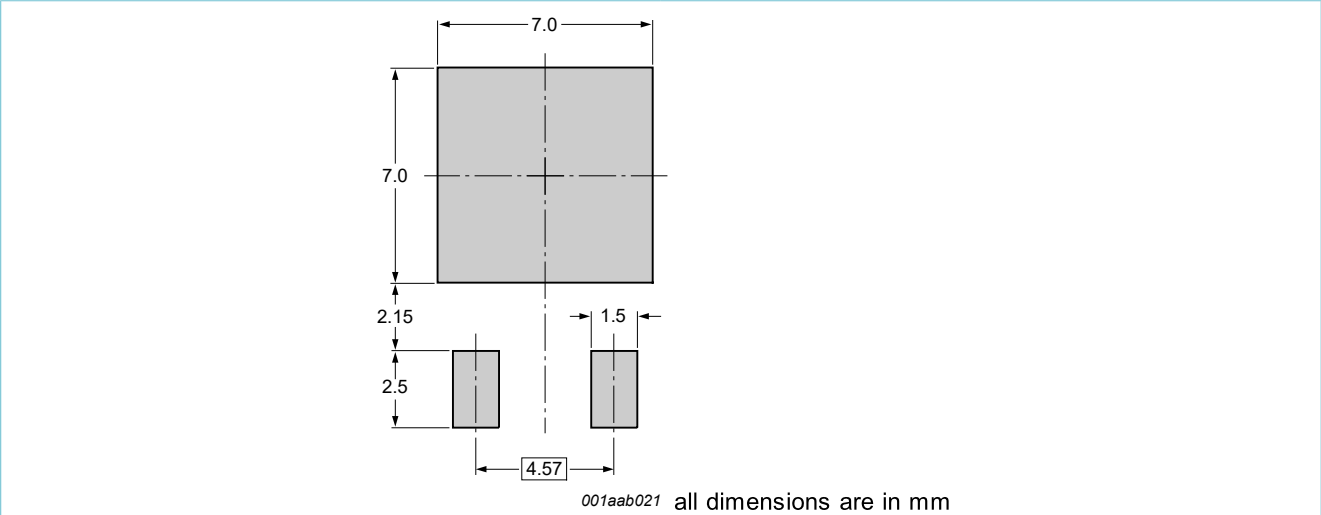
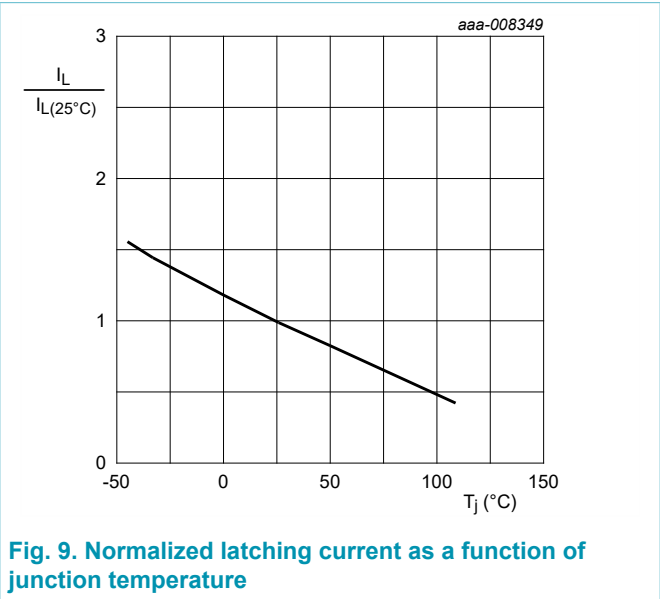
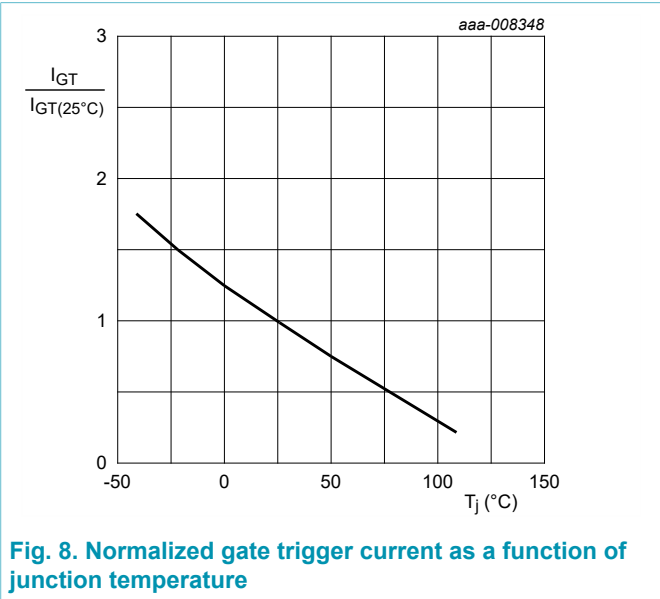


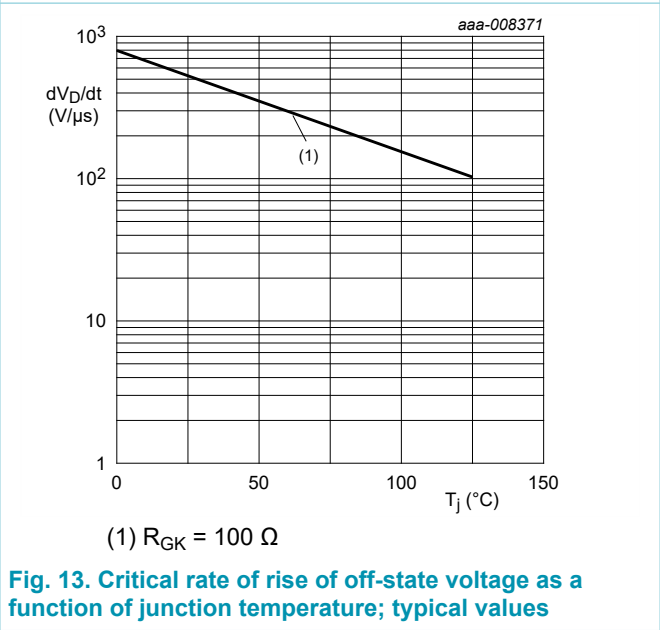
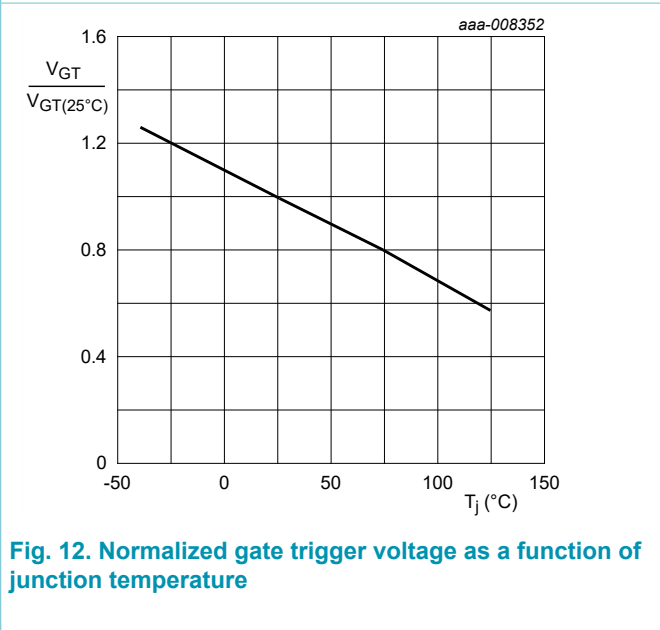
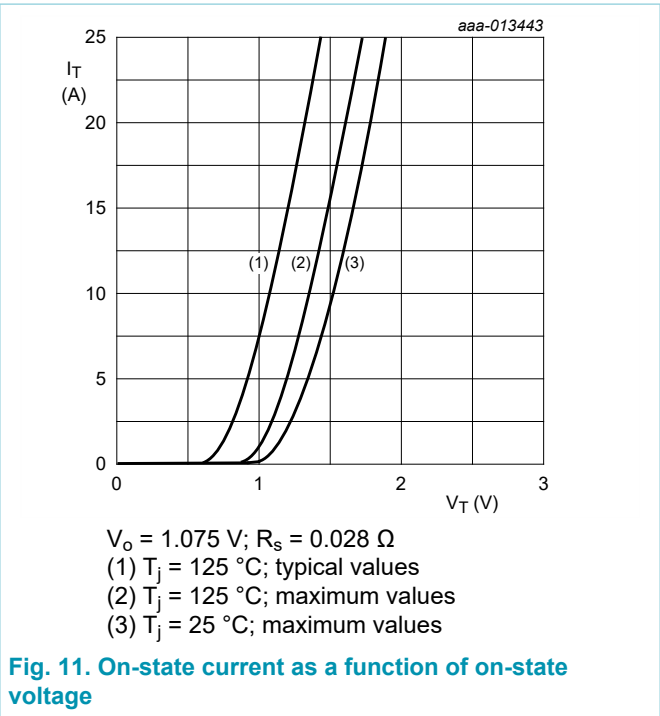
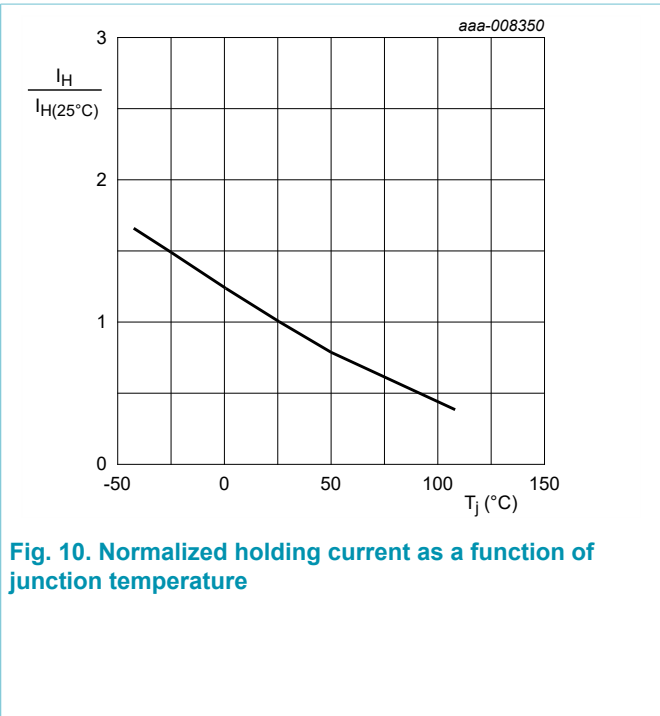
Fig. 7. Minimum footprint SOT428

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 8	20	50	200	μA
I_L	latching current	$V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 9	-	0.4	10	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 10	-	0.3	6	mA
V_T	on-state voltage	$I_T = 20\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 11	-	1.3	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 12	-	0.6	1	V
		$V_D = 650\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 110\text{ }^{\circ}\text{C}$; Fig. 12	0.1	0.2	-	V
I_D	off-state current	$V_D = 650\text{ V}$; $T_j = 125\text{ }^{\circ}\text{C}$	-	0.1	0.5	mA
I_R	reverse current	$V_R = 650\text{ V}$; $T_j = 125\text{ }^{\circ}\text{C}$	-	0.1	0.5	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 436\text{ V}$; $T_j = 125\text{ }^{\circ}\text{C}$; $R_{GK} = 100\text{ }\Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; Fig. 13	50	100	-	V/ μs





11. Package outline

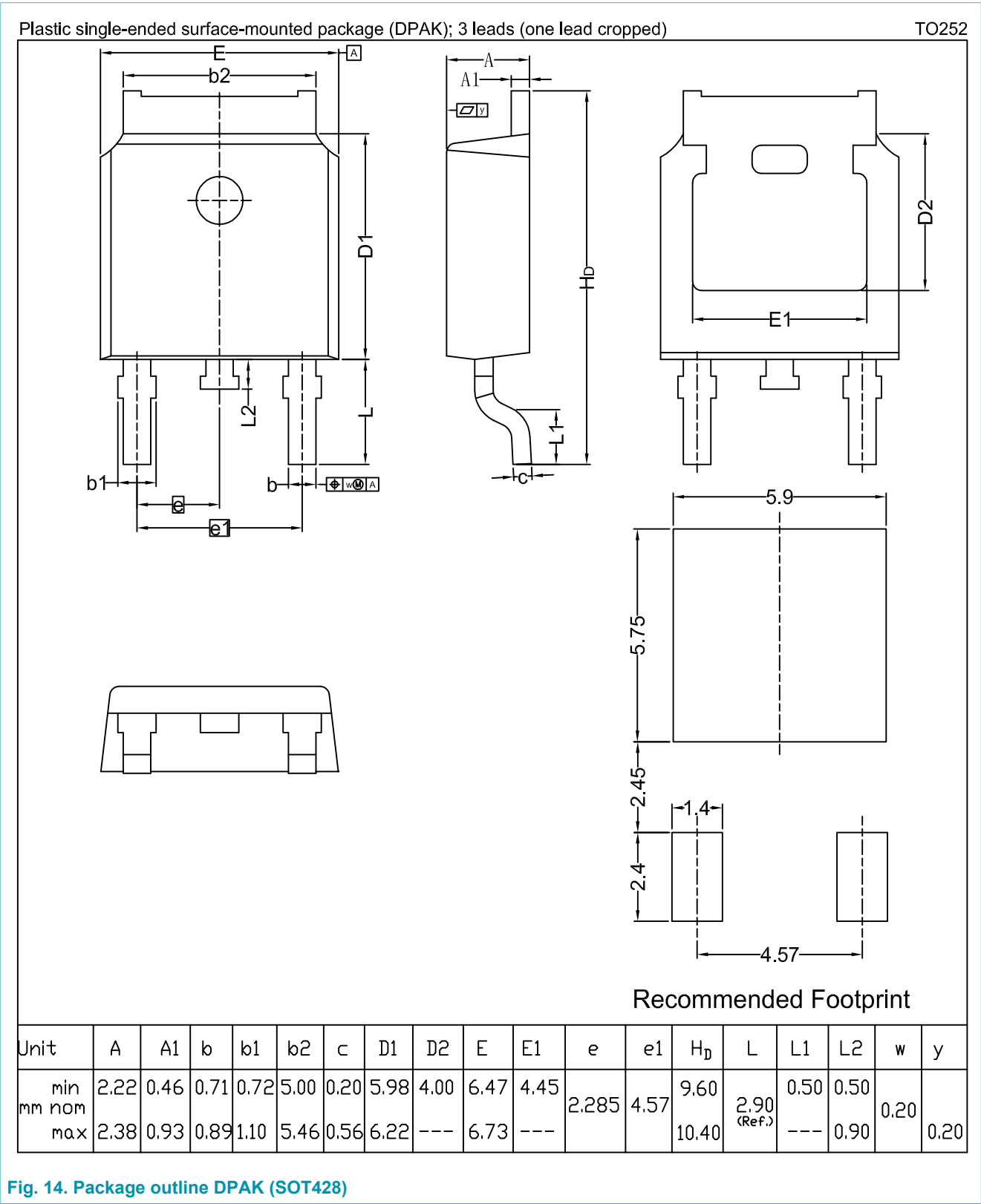


Fig. 14. Package outline DPAK (SOT428)

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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